

SOT702-2

plastic very thin fine-pitch ball grid array package; 56 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA56
Package type industry code	VFBGA56
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Mounting method type	S (surface mount)
Issue date	21-8-2014

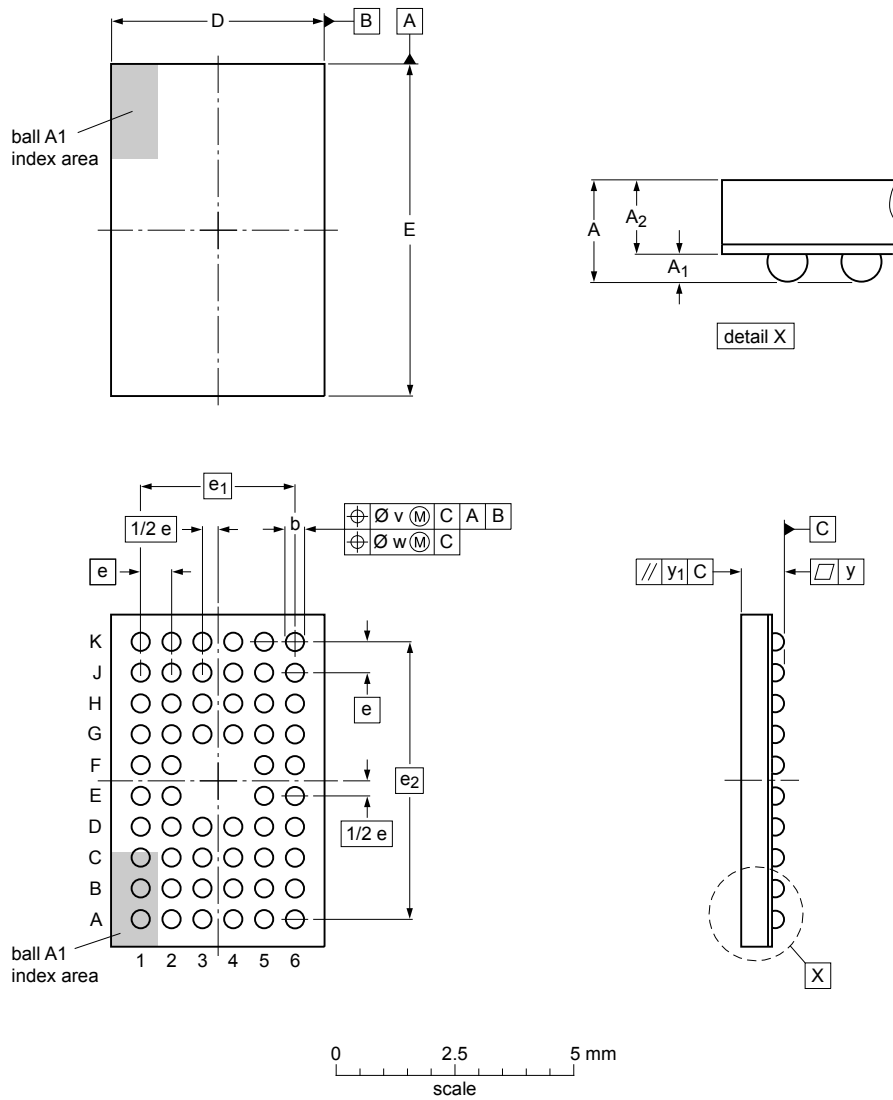
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.4	-	4.5	4.6	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	0.75	-	0.85	1	mm
A ₂	package height	0.55	-	0.6	0.7	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	56	-	



2. Package outline

VFBGA56: plastic very thin fine-pitch ball grid array package; 56 balls SOT702-2



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
max	1.00	0.30	0.70	0.35	4.6	7.1							
mm nom	0.85	0.25	0.60	0.30	4.5	7.0	0.65	3.25	5.85	0.15	0.08	0.1	0.1
min	0.75	0.20	0.55	0.25	4.4	6.9							

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT702-2					-14-07-10- 14-08-21

Fig. 1. Package outline VFBGA56 (SOT702-2)

3. Legal information

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